

QUAD DARLINGTON SWITCHES

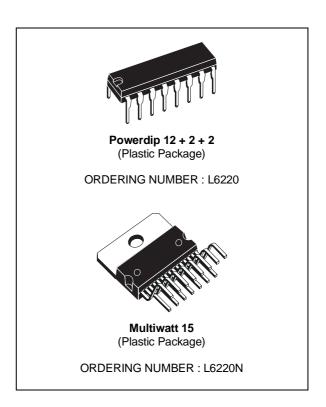
- TWO NON INVERTING + TWO INVERTING IN-PUTS WITH INHIBIT
- OUTPUT VOLTAGE UP TO 50V
- OUTPUT CURRENT UP TO 1.8A
- VERY LOW SATURATION VOLTAGE
- TTL COMPATIBLE INPUTS
- INTEGRAL FAST RECIRCULATION DIODES

DESCRIPTION

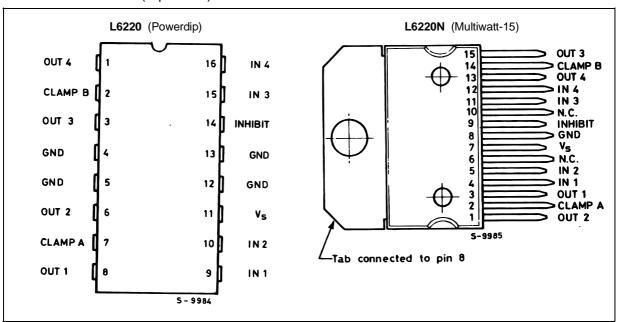
The L6220 monolithic quad darlington switch is designed for high current, high voltage switching applications. Each of the four switches is controlled by a logic input and all four are controlled by a common inhibit input. All inputs are TTL-compatible for direct connection to logic circuits.

Each switch consists of an open-collector darlington transistor plus a fast diode for switching applications with inductive loads. The emitters of the four switches are commoned. Any number of inputs and outputs of the same device may be paralleled.

Two versions are available: the L6220 mounted in a Powerdip 12 + 2 + 2 package and the L6220N mounted in a 15-lead Multiwatt package.



PIN CONNECTIONS (top views)

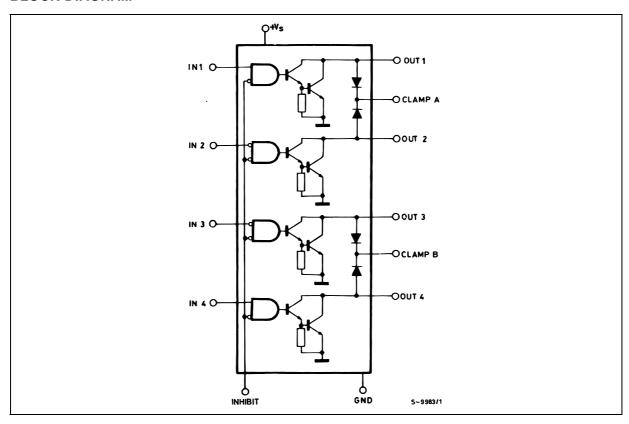


September 2003 1/12

PIN FUNCTIONS (see block diagram)

Name	Function
IN 1	Input to Driver 1
IN 2	Input to Driver 2
OUT 1	Output of Driver 1
OUT 2	Output of Driver 2
CLAMP A	Diode Clamp to Driver 1 and Driver 2
IN 3	Input to Driver 3
IN 4	Input to Driver 4
OUT 3	Output of Driver 3
OUT 4	Output of Driver 4
CLAMP B	Diode Clamp to Driver 3 and Driver 4
INHIBIT	Inhibit Input to all Drivers
Vs	Logic Supply Voltage
GND	Common Ground

BLOCK DIAGRAM



TRUTH TABLE

Inhibit	Input 1, 4	Power Out	Inhibit	Inputs 2, 3	Power Out
L	H	ON	エトト	L	ON
L	L	OFF		H	OFF
H	X	OFF		X	OFF

For each input : H = High levelL = Low level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vo	Ouput Voltage	50	V
Vs	Logic Supply Voltage	7	V
V _{IN} , V _{INH}	Input Voltage, Inhibit Voltage	Vs	
Ic	Continuous Collector Current (for each channel)	1.8	Α
I _C	Collector Peak Current (repetitive, duty cycle = 10 % t _{on} = 5 ms)	2.5	Α
Ic	Collector Peak Current (non repetitive, t = 10 μs)	3.2	Α
T _{op}	Operating Temperature Range (junction)	- 40 to + 150	°C
T _{stg}	Storage Temperature Range	- 55 to + 150	°C
I _{sub}	Output Substrate Current	350	mA
P _{tot}	$ \begin{array}{lll} \mbox{Total Power Dissipation} & \mbox{at } T_{\mbox{\tiny pins}} &=& 90^{\circ}\mbox{C (Powerdip)} \\ \mbox{at } T_{\mbox{\tiny case}} &=& 90^{\circ}\mbox{C (Multiwatt)} \\ \mbox{at } T_{\mbox{\tiny amb}} &=& 70^{\circ}\mbox{C (Powerdip)} \\ \mbox{at } T_{\mbox{\tiny amb}} &=& 70^{\circ}\mbox{C (Multiwatt)} \\ \end{array} $	4.3 20 1 2.3	W W W

THERMAL DATA

Symbol	Parameter		Powerdip	Multiwatt-15	Unit
R _{th j-pins}	Thermal Resistance Junction-pins	Max.	14	-	°C/W
R _{th j-case}	Thermal Resistance Junction-case	Max.	-	3	°C/W
R _{th j-amb}	Thermal Resistance Junction-ambient	Max.	80	35	°C/W

ELECTRICAL CHARACTERISTICS

Refer to the test circuits Fig. 1 to Fig.9 ($V_S = 5V$, $T_{amb} = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Parameter Test Conditions			Max.	Unit
Vs	Logic Supply Voltage		4.5		5.5	V
Is	Logic Supply Current	All Outputs ON, $I_C = 0.7A$ All Outputs OFF			20 20	mA MA
V _{CE} (sus)	Output Sustaining Voltage	I_C =100mA, $V_{INH} = V_{INH}H$	46			V
ICEX	Output Leakage Current	$V_{CE} = 50V$, $V_{IN 1.4} = V_{INH}H$			1	mA
V _{CE} (sat)	Collector Emitter Saturation Voltage (one output on ; all others off.)	$\begin{array}{l} V_{s} = 4.5V, V_{IN 2.3} = V_{IN}L \\ V_{INH} = V_{INHL} \\ I_{C} = 0.6A \\ I_{C} = 1A \\ I_{C} = 1.8A \end{array}$			1 1.2 1.6	V
V _{IN} L, V _{INH} L	Input Low Voltage				0.8	V
I _{IN} L, I _{INH} L	Input Low Current	$V_{IN} = V_{IN}L$, $V_{INH} = V_{INH}L$			- 100	μΑ
V _{IN} H, V _{INH} H	Input High Voltage		2.0			V
I _{IN} H, I _{INH} H	Input High Current	$V_{IN} = V_{IN}H$, $V_{INH} = V_{INH}H$			± 10	μΑ
I_R	Clamp Diode Leakage Current	$V_R = 50V$, $V_{INH} = V_{INH}H$			100	μΑ
V _F	Clamp Diode Forward Voltage	I _F = 1A I _F = 1.8A			1.6 2.0	V V
t _{d (on)}	Turn on Delay Time	$V_p = 5V$, $R_L = 10\Omega$			2	μs
t _{d (off)}	Turn off Delay Time	$V_p = 5V, R_L = 10\Omega$			5	μS
ΔI _s	Logic Supply Current Variation	$V_{IN} = 5V$, $V_{EN} = 5V$ $I_{out} = -300$ mA for each Channel			120	mA

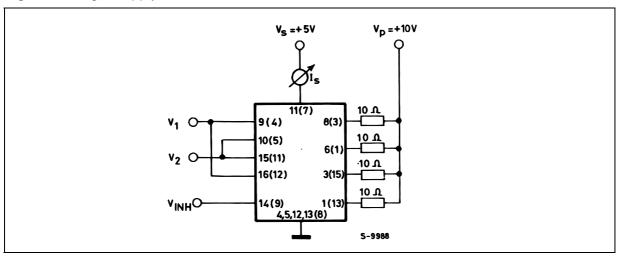


TEST CIRCUITS

(X) = Referred to Multiwatt package

X = Referred to Powerdip package

Figure 1: Logic Supply Current.



Set V $_1$ = 4.5V, V $_2$ = 0.8V, V $_{\text{INH}}$ = 4.5V or V $_1$ = 0.8V, V $_2$ = 4.5V, V $_{\text{INH}}$ = 0.8 for Is (all outputs off). Set V $_1$ = 2V, V $_2$ = 0.8V, V $_{\text{INH}}$ = 0.8V for Is (all outputs on).

Figure 2: Output Sustaining Voltage.

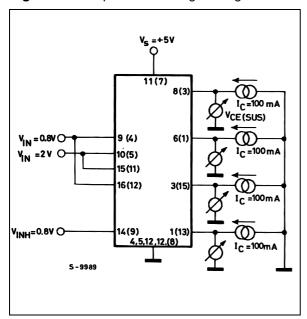


Figure 3: Output Leakage Current.

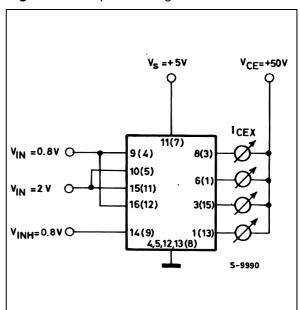


Figure 4 : Collector-emitter Saturation

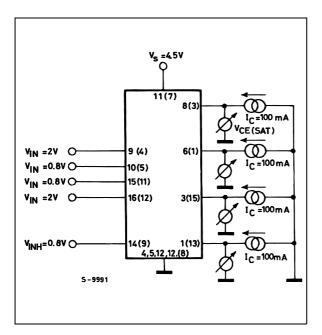


Figure 6 : Clamp Diode Leakage Current.

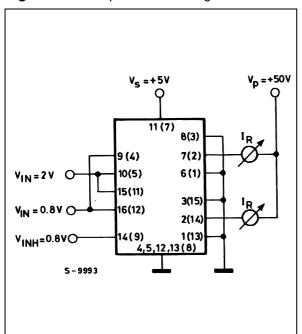
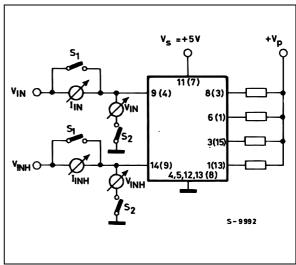


Figure 5: Logic Input Characteristics.



Set S ₁, S ₂ open, V _{IN}, V _{INH} = 0.8V for I _{IN} L, I _{INH} L Set S ₁, S ₂ open, V _{IN}, V _{INH} = 2V for I _{IN} H, I _{INH} H

Set S₁, S₂ open, V_{IN}, V_{INH} = 2V_{IOI} I_{IN} I_I, I_{INH} II Set S₁, S₂ close, V_{IN}, V_{INH} = 0.8V for V_{IN} L, V_{INH} L

Set S₁, S₂ close, V_{IN}, V_{INH} = 2V for V_{IN} H, V_{INH} H.

Figure 7: Clamp Diode Forward Voltage.

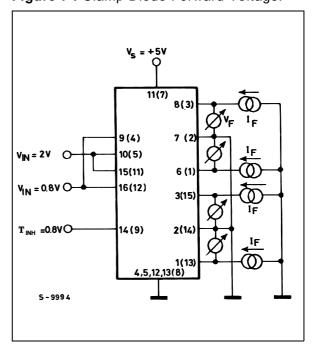


Figure 8: Switching Times Test Circuit.

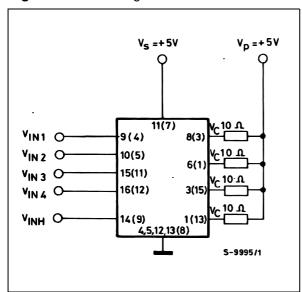


Figure 10 : Collector Saturation Voltage versus Collector Current

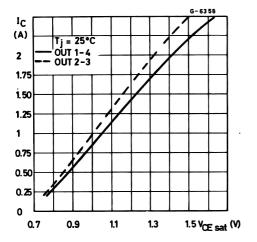


Figure 9: Switching Times Waveforms.

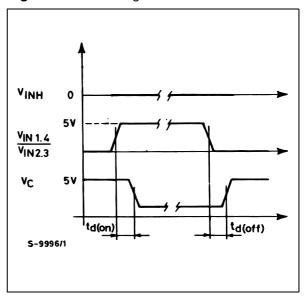


Figure 11: Free- wheeling Diode ForwardVoltage versus Diode Current

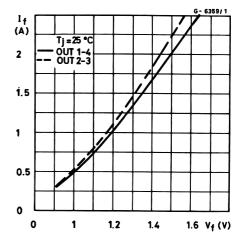


Figure 12 : Collector Saturation Voltage versus Junction Temperature at IC = 1A

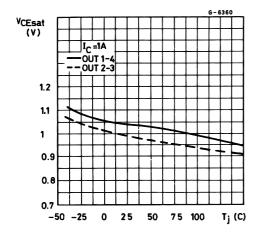


Figure 14: Collector Saturation Voltage versus Junction Temperature at IC = 1.8A

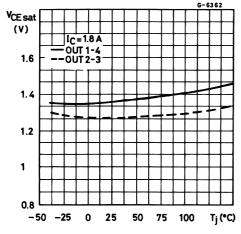


Figure 16.

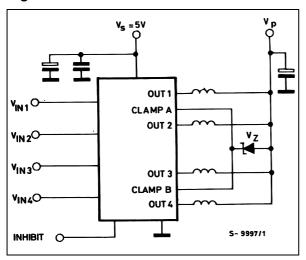


Figure 13: Free-wheeling Diode Forward Voltage versus Junction Temperature at If = 1A

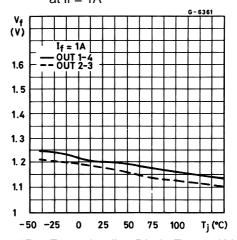


Figure 15 : Free-wheeling Diode Forward Voltage versus Junction Temperature at $I_F = 1.8A$

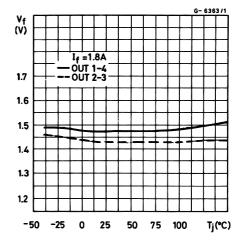
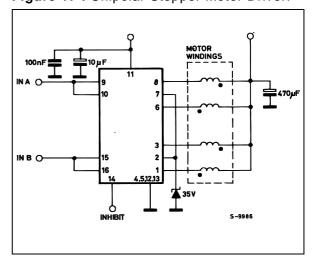


Figure 17: Unipolar Stepper Motor Driver.



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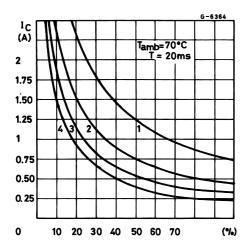
APPLICATION INFORMATION

When inductive loads are driven by L6220/N, a zener diode in series with the integral free-wheeling diodes increases the voltage across which energy stored in the load is discharged and therefore speeds the current decay (Fig. 16). For reliability it is suggested that the zener is chosen so that $V_p + V_z < 35 \text{ V}$.

The reasons for this are two fold:

 The zener voltage changes in temperature and current.

Figure 18: Allowed Peak Collector-current versus Duty Cycle for 1, 2, 3 or 4 Contemporary Working Outputs (L6220).



MOUNTING INSTRUCTION

The $R_{th\,j\text{-amb}}$ of the L6220 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (Fig. 20) or to an external heatsink (Fig. 21).

The diagram of figure 22 shows the maximum dissipable power P_{tot} and the $R_{th\ j-amb}$ as a function of the side " α " of two equal square copper areas hav-

2) The instantaneous power must be limited to avoid the reverse second breakdown. The particular internal logic allows an easier full step driving using only two input signals.

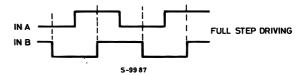
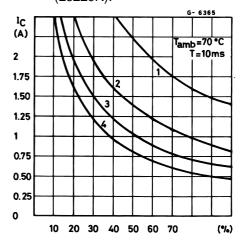


Figure 19: Allowed Peak Collector Cur-rent versus Duty Cycle for 1, 2, 3 or 4 Contemporary Working Outputs (L6220N).



ing a thickness of $35\mu\,$ (1.4 mils). During soldering the pins temperature must not exceed 260 °C and the soldering time must not be longer than 12 seconds

The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 20 : Example of P.C. Board Copperarea which is used as Heatsink

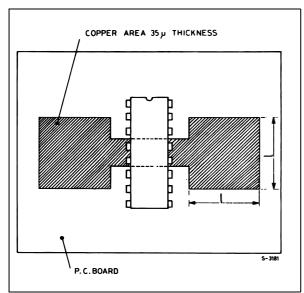


Figure 22 : Maximum Dissipable Power and Junction to Ambient Thermal Resistance versus Side "α"

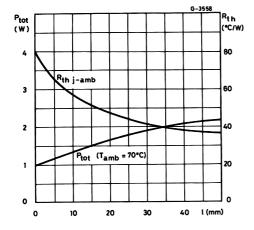


Figure 21: External Heatsink Mounting Example

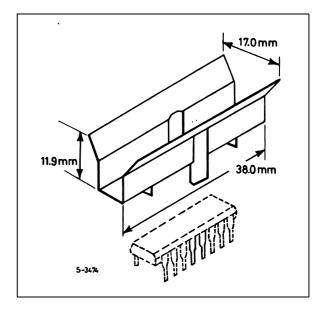
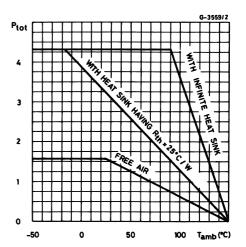
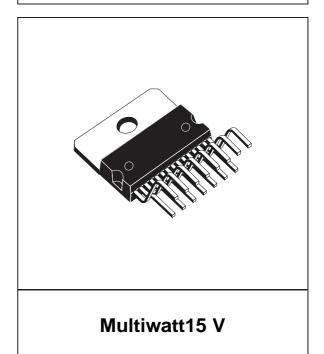


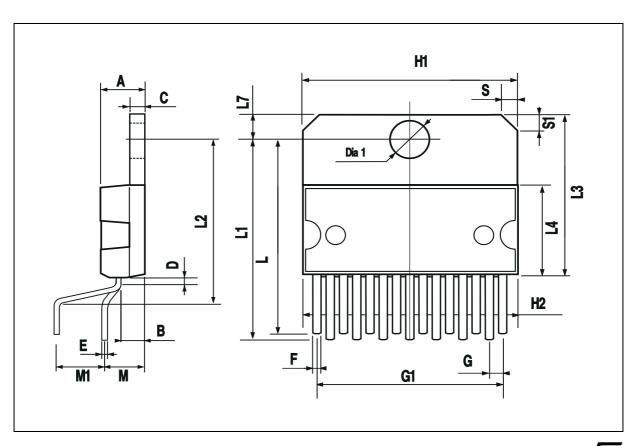
Figure 23: Maximum Allowable Power Dissipation versus Ambient Temperature



DIM.		mm			inch	
DIN.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			5			0.197
В			2.65			0.104
С			1.6			0.063
D		1			0.039	
Е	0.49		0.55	0.019		0.022
F	0.66		0.75	0.026		0.030
G	1.02	1.27	1.52	0.040	0.050	0.060
G1	17.53	17.78	18.03	0.690	0.700	0.710
H1	19.6			0.772		
H2			20.2			0.795
L	21.9	22.2	22.5	0.862	0.874	0.886
L1	21.7	22.1	22.5	0.854	0.870	0.886
L2	17.65		18.1	0.695		0.713
L3	17.25	17.5	17.75	0.679	0.689	0.699
L4	10.3	10.7	10.9	0.406	0.421	0.429
L7	2.65		2.9	0.104		0.114
М	4.25	4.55	4.85	0.167	0.179	0.191
M1	4.63	5.08	5.53	0.182	0.200	0.218
S	1.9		2.6	0.075		0.102
S1	1.9		2.6	0.075		0.102
Dia1	3.65		3.85	0.144		0.152

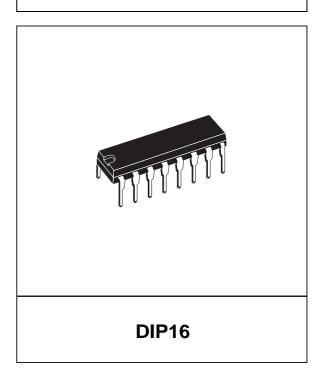
OUTLINE AND MECHANICAL DATA

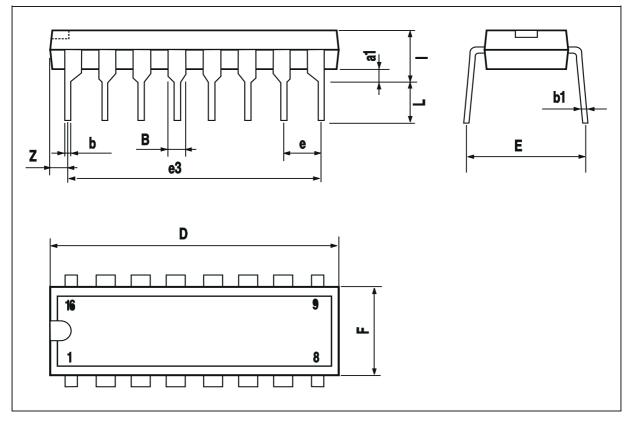




DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
В	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
Е		8.5			0.335	
е		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050

OUTLINE AND MECHANICAL DATA





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